

TM50P02AD

P -Channel Enhancement Mosfet

General Description

- Low $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

Applications

- Load switch
- PWM

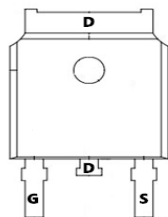
General Features

$V_{DS} = -20V$ $I_D = -48A$

$R_{DS(ON)} = 16m\Omega$ (typ.) @ $V_{GS} = -4.5V$

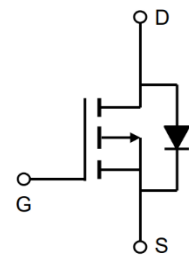
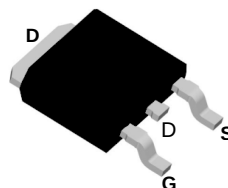
100% UIS Tested

100% R_g Tested



Marking: 50P02A

D:TO-252-3L



Absolute Maximum Ratings (TC=25°C unless otherwise noted)

Symbol	Parameter		Rating	Unit
V_{DSS}	Drain-Source Voltage		-20	V
V_{GSS}	Gate-Source Voltage		± 12	
I_D^a	Continuous Drain Current ($V_{GS} = -4.5V$)	$T_A = 25^\circ C$	-48	A
		$T_A = 70^\circ C$	-30	
I_{DM}^a	Pulsed Drain Current ($V_{GS} = -4.5V$)		-244	
I_S^a	Diode Continuous Forward Current		-10	
T_J	Maximum Junction Temperature		150	$^\circ C$
I_{AS}^d	Avalanche Current, Single pulse	$L = 0.5mH$	-12	A
E_{AS}^d	Avalanche Energy, Single pulse	$L = 0.5mH$	36	mJ
T_{STG}	Storage Temperature Range		-55 to 150	$^\circ C$
P_D^c	Maximum Power Dissipation	$T_C = 25^\circ C$	31.25	W
		$T_C = 100^\circ C$	12.5	
$R_{\theta JA}^{a,b}$	Thermal Resistance-Junction to Ambient	$t \leq 10s$	40	$^\circ C/W$
		Steady State	80	
$R_{\theta JC}^c$	Thermal Resistance-Junction to Case		4	$^\circ C/W$

Note * : Package limited.

a : Surface Mounted on $1in^2$ pad area, $t \leq 10sec$.

b : Maximum under Steady State conditions is $75^\circ C/W$.

c : The power dissipation P_D is based on $T_{J(MAX)} = 150^\circ C$, and it is useful for reducing junction-to-case thermal resistance ($R_{\theta JC}$) when additional heat sink is used.

d : UIS tested and pulse width limited by maximum junction temperature $150^\circ C$ (initial temperature $T_J = 25^\circ C$)

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Electrical Characteristics ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

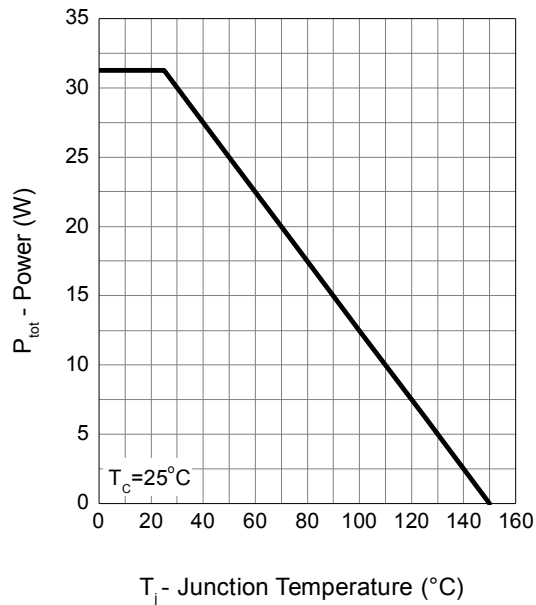
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =-250μA	-20	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-16V, V _{GS} =0V T _J =85°C	-	-	-1	μA
			-		-30	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =-250μA	-0.5	-0.7	-1	V
I _{GSS}	Gate Leakage Current	V _{GS} =±12V, V _{DS} =0V	-	-	±10	μA
R _{DS(ON)} ^e	Drain-Source On-state Resistance	V _{GS} =-4.5V, I _{DS} =-11A	-	16	19	mΩ
		V _{GS} =-2.5V, I _{DS} =-6A	-	20	23	
Diode Characteristics						
V _{SD} ^e	Diode Forward Voltage	I _{SD} =-1A, V _{GS} =0V	-	-0.7	-1	V
t _{rr} ^f	Reverse Recovery Time	I _{SD} =-11A, dI _{SD} /dt=100A/μs	-	63	-	ns
Q _{rr} ^f	Reverse Recovery Charge		-	54	-	nC
Dynamic Characteristics ^f						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-10V, Frequency=1.0MHz	-	1220	-	pF
C _{oss}	Output Capacitance		-	320	-	
C _{rss}	Reverse Transfer Capacitance		-	290	-	
t _{d(ON)}	Turn-on Delay Time	V _{DD} =-10V, R _L =10Ω, I _{DS} =-1A, V _{GEN} =-4.5V, R _G =6Ω	-	9	-	ns
t _r	Turn-on Rise Time		-	13	-	
t _{d(OFF)}	Turn-off Delay Time		-	26	-	
t _f	Turn-off Fall Time		-	167	-	
Gate Charge Characteristics ^f						
Q _g	Total Gate Charge	V _{DS} =-10V, V _{GS} =-4.5V, I _{DS} =-11A	-	25	-	nC
Q _{gs}	Gate-Source Charge		-	1.6	-	
Q _{gd}	Gate-Drain Charge		-	11	-	

Note e : Pulse test; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

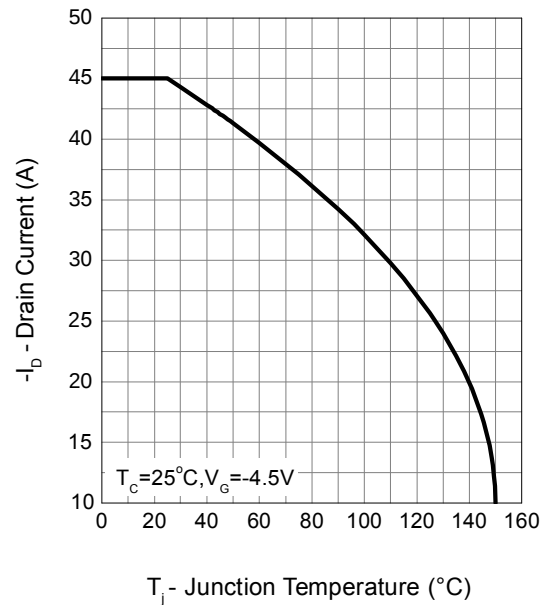
Note f : Guaranteed by design, not subject to production testing.

Typical Operating Characteristics

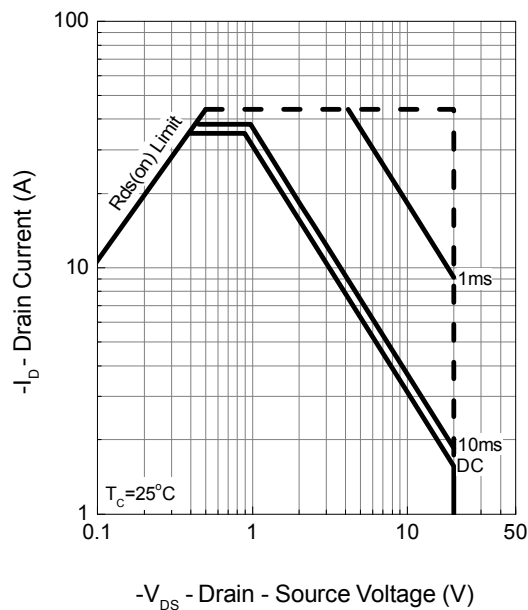
Power Dissipation



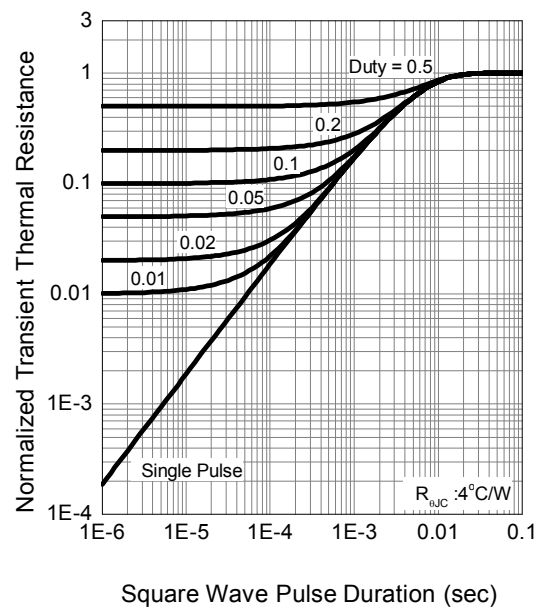
Drain Current



Safe Operation Area



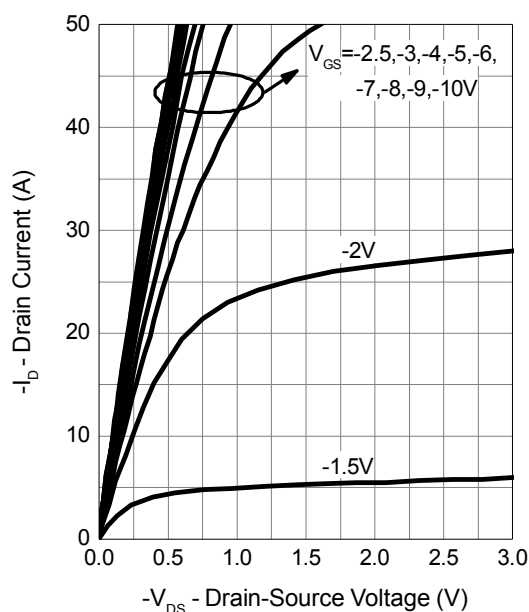
Thermal Transient Impedance



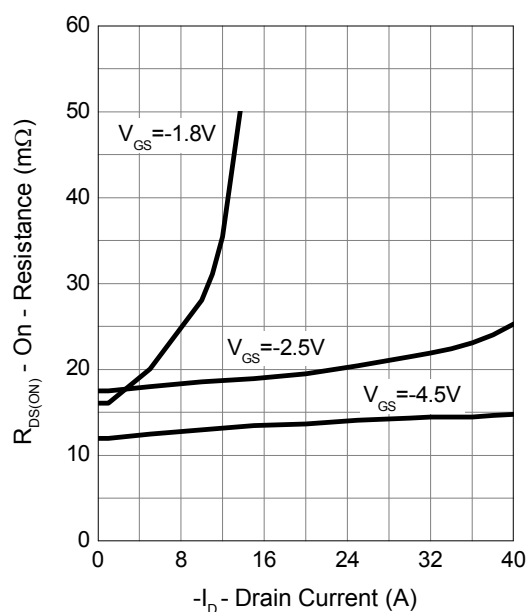
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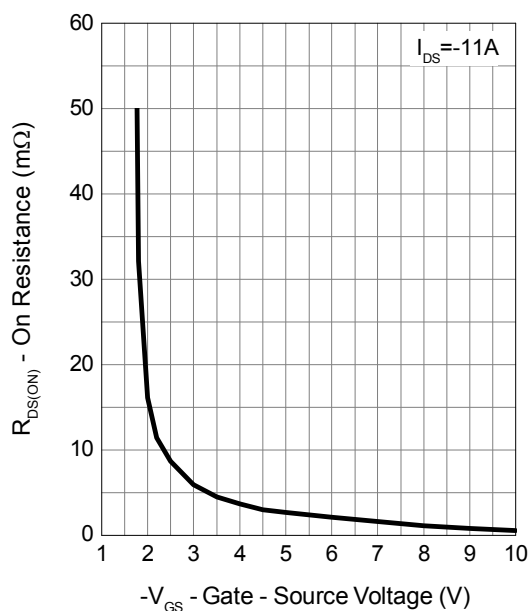
Output Characteristics



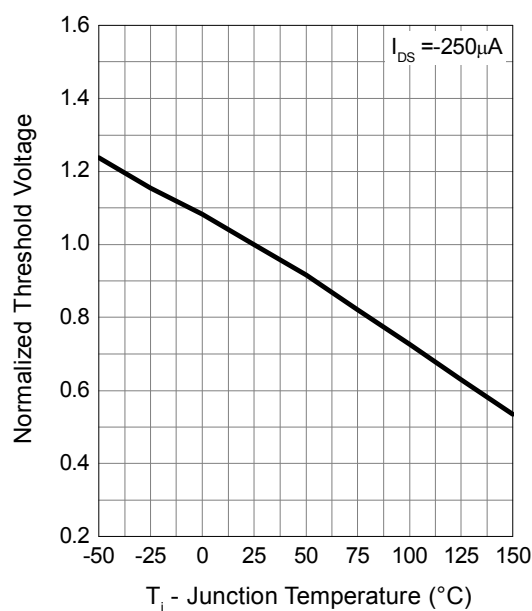
Drain-Source On Resistance



Gate-Source On Resistance



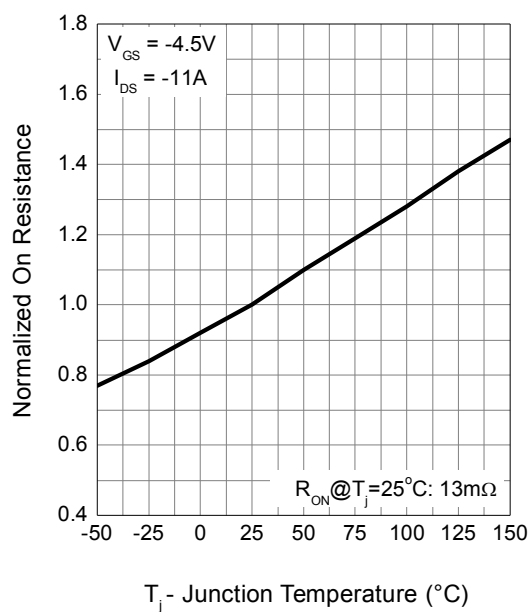
Gate Threshold Voltage



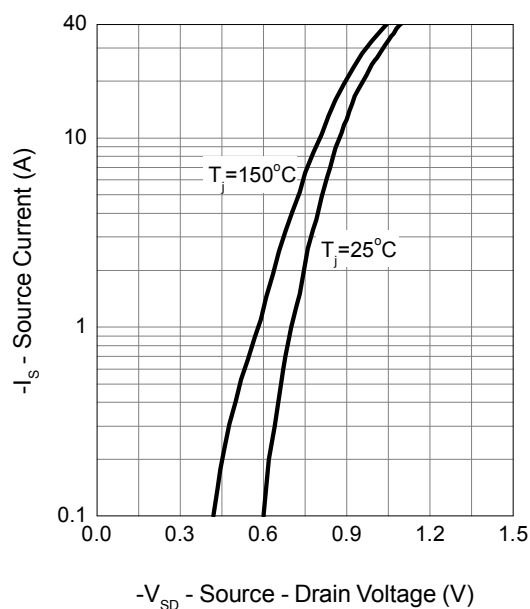
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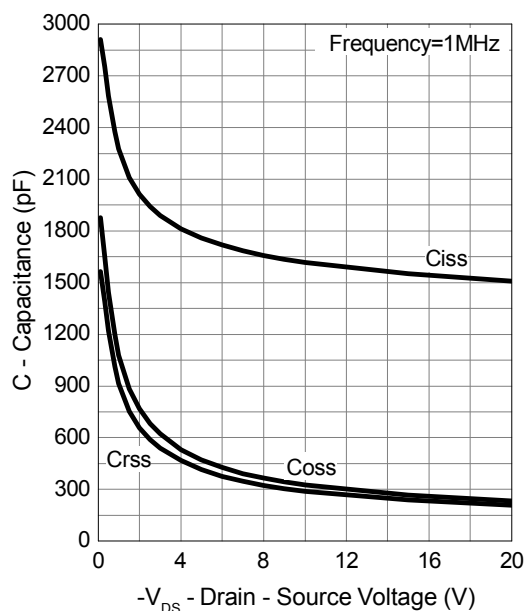
Drain-Source On Resistance



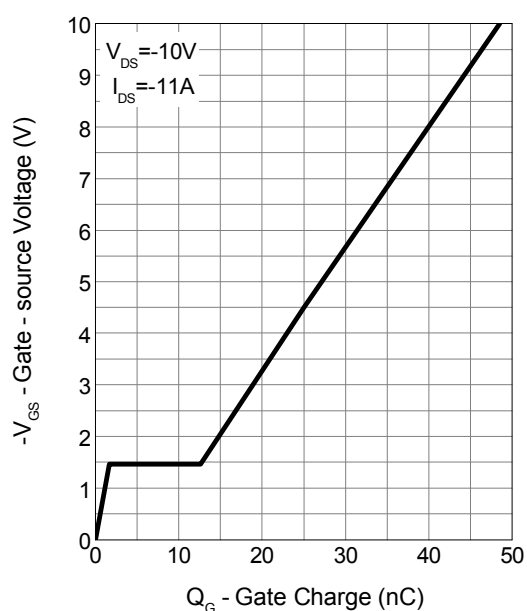
Source-Drain Diode Forward



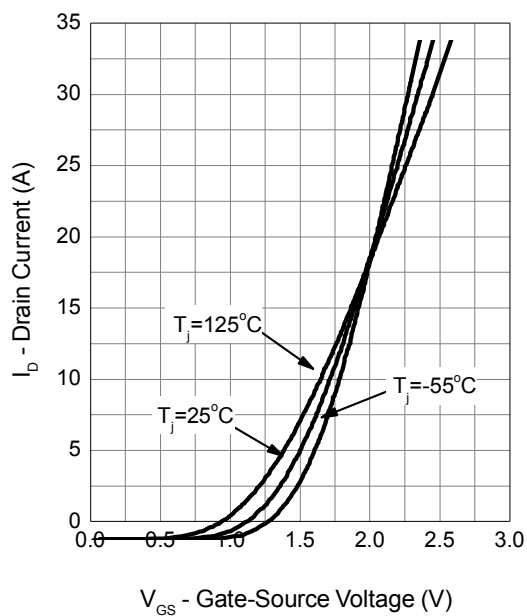
Capacitance



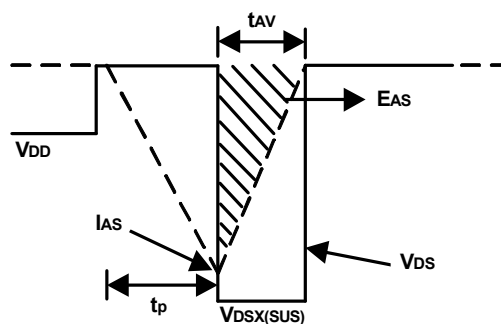
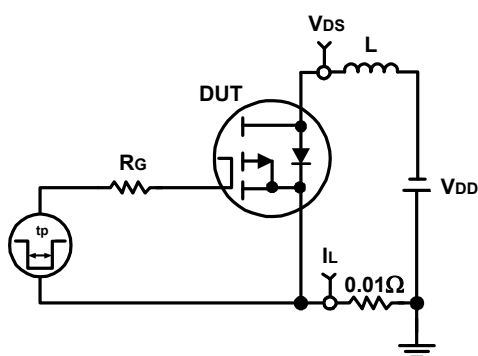
Gate Charge



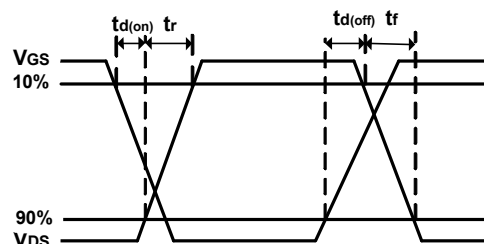
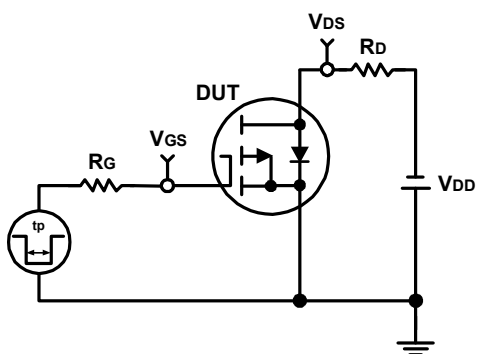
Transfer Characteristics



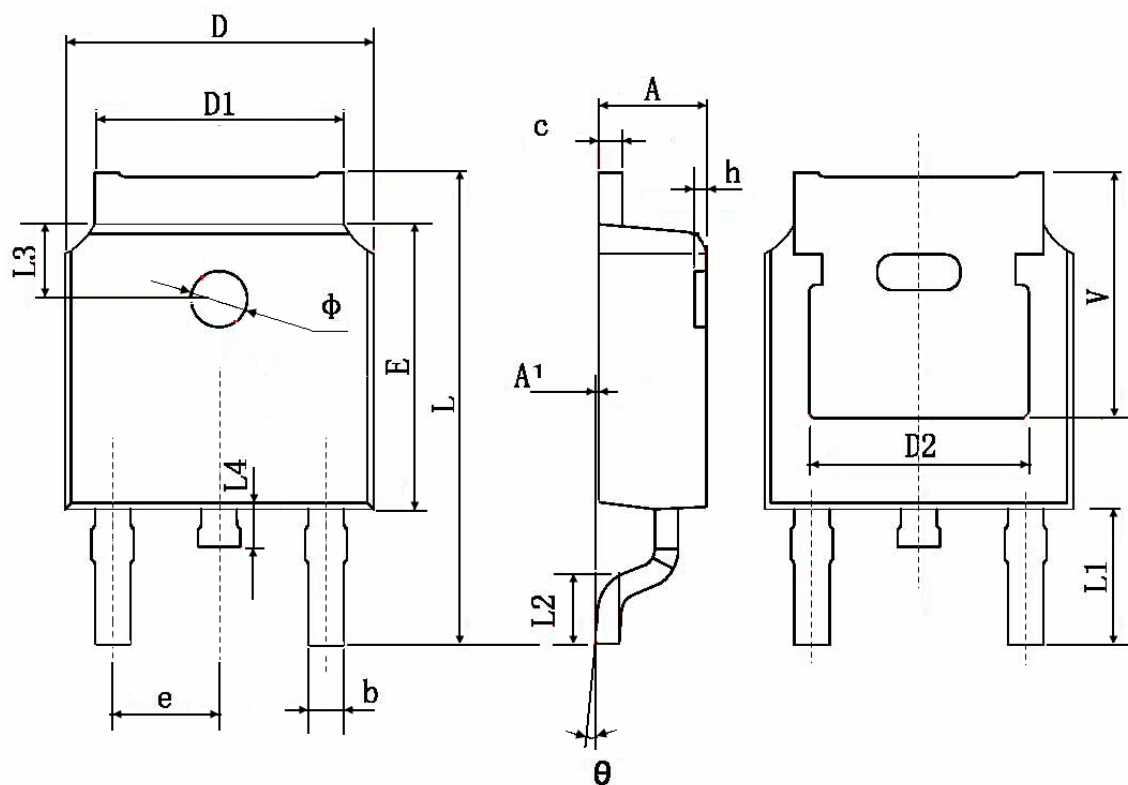
Avalanche Test Circuit and Waveforms



Switching Time Test Circuit and Waveforms



Package Mechanical Data: TO-252-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	